

BAS21HT1G, NSVBAS21HT1G, NSVBAS21HT3G

High Voltage Switching Diode

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_R	250	Vdc
Repetitive Peak Reverse Voltage	V_{RRM}	250	Vdc
Peak Forward Current	I_F	200	mAdc
Repetitive Peak Forward Current	I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current, 60 Hz	$I_{FSM(surge)}$	625	mAdc
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^\circ\text{C}$ prior to surge)	I_{FSM}		A
$t = 1\ \mu\text{s}$		20	
$t = 10\ \mu\text{s}$		20	
$t = 100\ \mu\text{s}$		10	
$t = 1\ \text{ms}$		4	
$t = 1\ \text{s}$		1	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	200 1.57	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

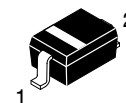
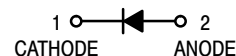
1. FR-5 Minimum Pad



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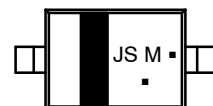
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HIGH VOLTAGE SWITCHING DIODE



SOD-323
CASE 477
STYLE 1

MARKING DIAGRAM



JS = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

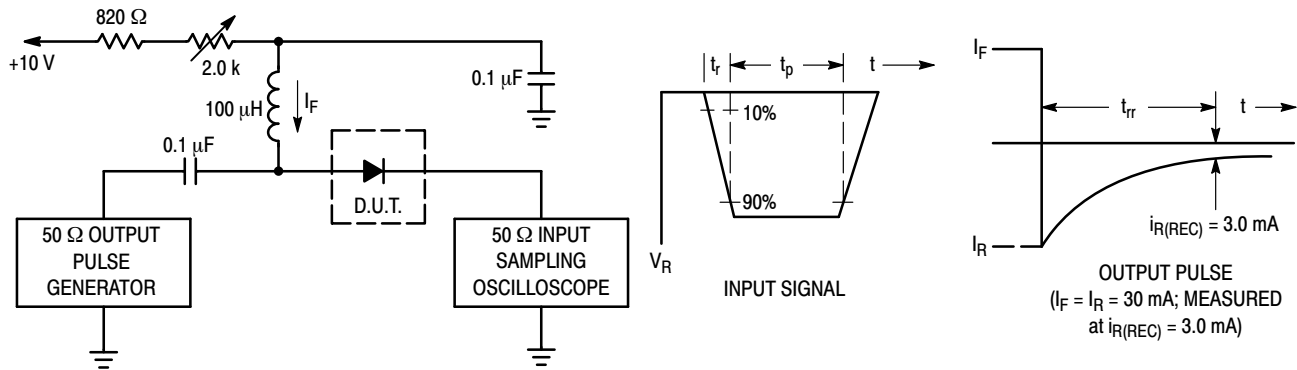
Device	Package	Shipping†
BAS21HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
NSVBAS21HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
NSVBAS21HT3G	SOD-323 (Pb-Free)	10000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current ($V_R = 200\text{ Vdc}$) ($V_R = 200\text{ Vdc}$, $T_J = 150^\circ\text{C}$)	I_R	–	0.1 100	μA dc
Reverse Breakdown Voltage ($I_{BR} = 100\text{ }\mu\text{A}$ dc)	$V_{(BR)}$	250	–	Vdc
Forward Voltage ($I_F = 100\text{ mA}$ dc) ($I_F = 200\text{ mA}$ dc)	V_F	–	1000 1250	mV
Diode Capacitance ($V_R = 0$, $f = 1.0\text{ MHz}$)	C_D	–	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30\text{ mA}$ dc, $R_L = 100\text{ }\Omega$)	t_{rr}	–	50	ns



- Notes:
1. A 2.0 kΩ variable resistor adjusted for a Forward Current (I_F) of 30 mA.
 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 30 mA.
 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

BAS21HT1G, NSVBAS21HT1G, NSVBAS21HT3G

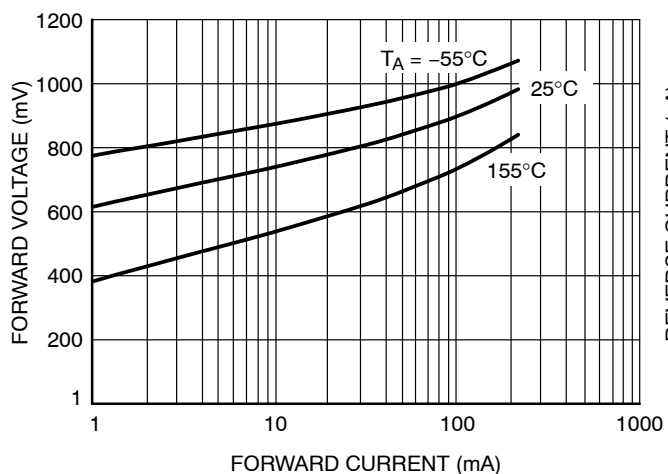


Figure 2. Forward Voltage

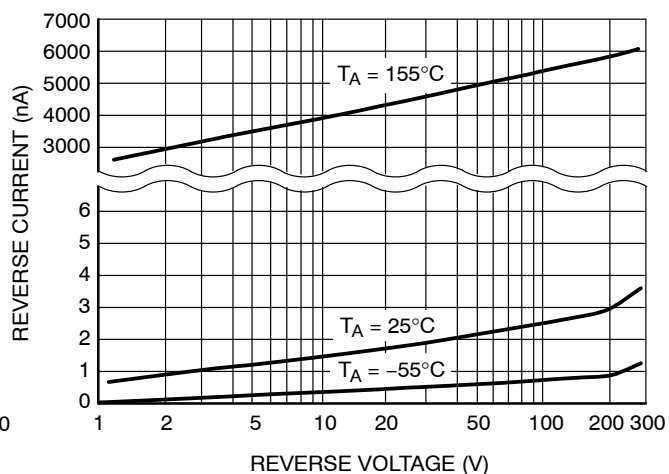


Figure 3. Reverse Leakage

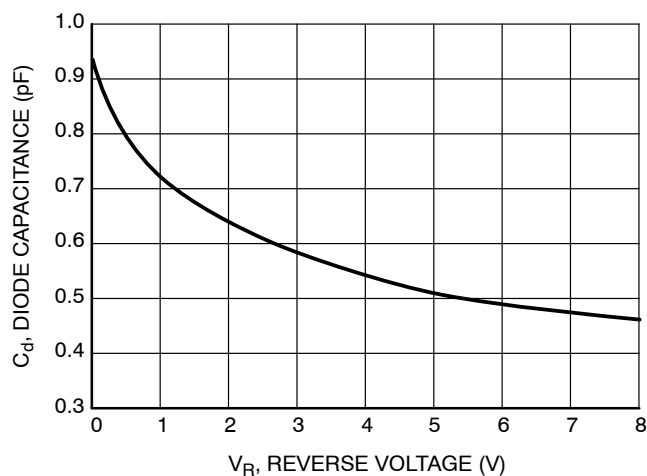


Figure 4. Diode Capacitance

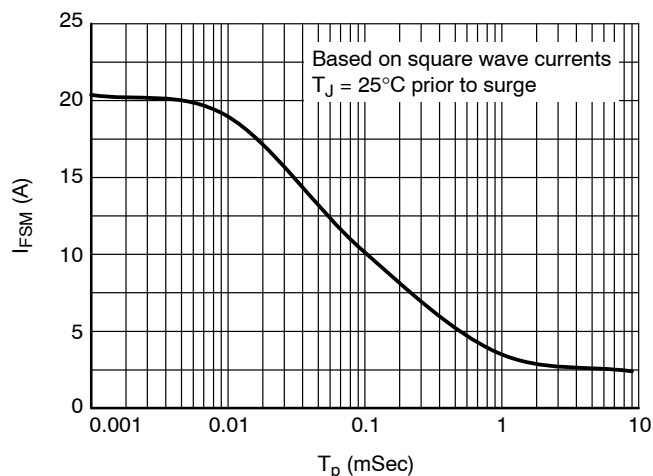
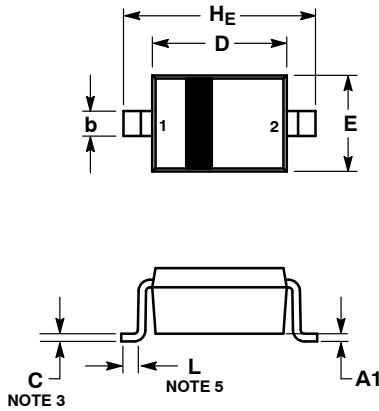


Figure 5. Maximum Non-repetitive Peak Forward Current as a Function of Pulse Duration, Typical Values

BAS21HT1G, NSVBAS21HT1G, NSVBAS21HT3G

PACKAGE DIMENSIONS

SOD-323
CASE 477-02
ISSUE G



NOTES:

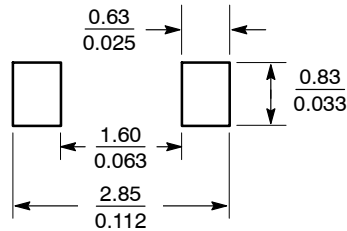
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105


STYLE 1:

- PIN 1. CATHODE
- ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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